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(54) **ELECTRICAL CONNECTION PAD WITH
ENHANCED SOLDERABILITY AND
CORRESPONDING METHOD FOR LASER
TREATING AN ELECTRICAL CONNECTION
PAD**

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(57) **ABSTRACT**

The invention concerns an electrical connection pad (10') for providing an electrical connection between components of an electronic system, wherein the electrical connection pad comprises: a metallic layer (12); and a laser induced periodic surface structure (20), LIPSS, formed on an external surface (16) of the electrical connection pad (10) and exposing the metallic layer (12) and a method for correspondingly laser-treating an electrical connection pad (10).

